Ball Grid Array (BGA, 1.27mm Pitch)

Specifications

Insulation Resistance: Dielectric Withstanding Voltage: 100V AC for 1 minute **Contact Resistance:** Operating Temperature Range: -55°C to +150°C

1,000M min. at 100V DC 30m max. at 10mA/20mV max. -40°C to +170°C 30g per pin approx. 10,000 insetions

Contact Force: Mating Cycles:

Features

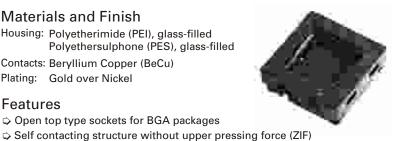
Materials and Finish

Housing: Polyetherimide (PEI), glass-filled Polyethersulphone (PES), glass-filled Contacts: Beryllium Copper (BeCu) Plating: Gold over Nickel

⇔ Open top type sockets for BGA packages

damage to the coplanarity of the solder balls

Contacting structure to nip the sides of solder balls to lower

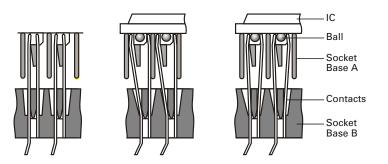


Part Number (Details)

NP2	/6	—	11	05	22	—	*	- (*
Series	No.								
No. of Contact Pins (.AC-types are depopulated base sockets)									
Design Number									
Positioning Pin Options (see PCB):									
	Pos.	pin '	A'	Pos	. pin	'B'	_		
1 =	Wit	h		With			_		
2 =	With			Without					
<u>2 =</u> 3 =	Without			With			-		
4 =	Wit	hou	t	V	Vitho	ut	-		

Contact Terminal Length and Form

Yamaichi's 2-point Tweezer Contact



Since the solder balls are touched by two contacts on each side, the solder ball damage can be minimized; additional features are low actuation force and compact socket size

We have depopulated versions from existing NP276 base sockets.

As new versions are continually being tooled up we rcommend

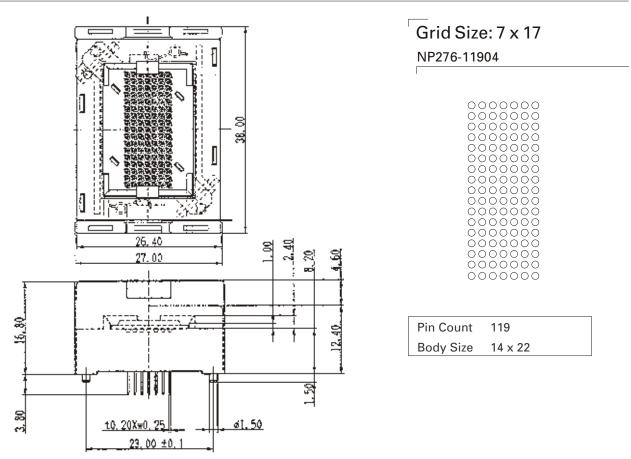
to contact Yamaichi for your specific pin count

and matching IC

Applicable Base Socket and IC Dimensions

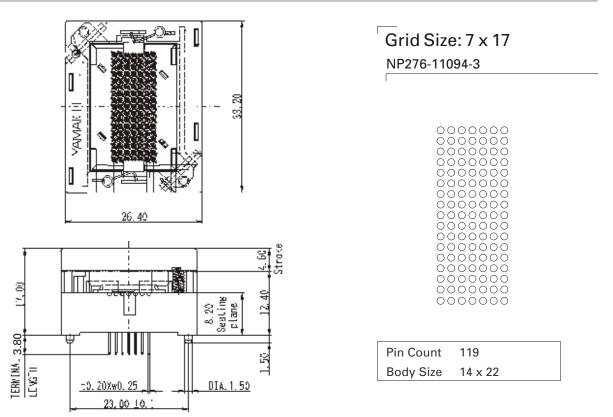
Part	Pin		IC Dimensions		Base Sockets	
Number	Count	Pitch	Grid Size	Body Size	(see page)	
NP276-11904	119	1.27	7 x 17	14 x 22	2	
NP276-11904-3	119	1.27	7 x 17	14 x 22	2	
NP276-15316	153	1.27	9 x 17	14 x 22	3	
NP276-16951	169	1.27	13 x 13	17 x 17	4	
NP276-25626	256	1.27	16 x 16	21 x 21	5	
NP276-37206	372	1.27	20 x 20	27 x 27	6	
NP276-40009	400	1.27	20 x 20	27 x 27	7	
NP276-59608	596	1.27	26 x 26	35 x 35	8	
NP276-65227	652	1.27	28 x 28	37.5 x 37.5	9	
NP276-87318	873	1.27	31 x 31	40 x 40	10	
NP276-110522	1105	1.27	35 x 35	45 x 45	11	

Outline Socket Dimensions (27.00 x 38.00mm)

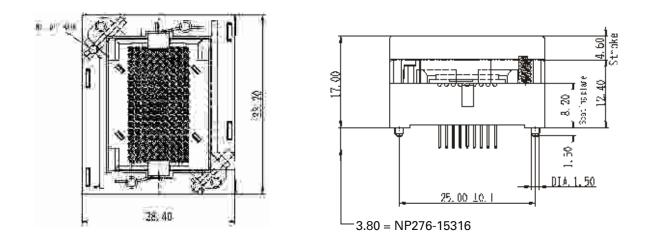


Base Socket NP276-11094-3

Outline Socket Dimensions (26.40 x 32.20mm)



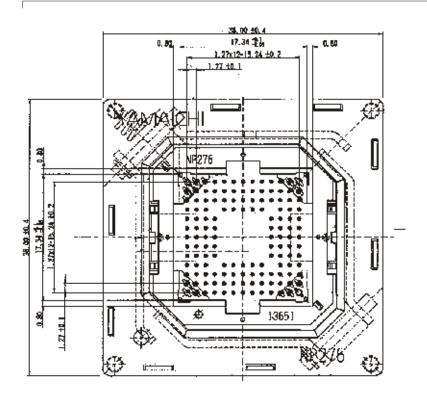
Outline Socket Dimensions (28.40 x 33.20mm)



Grid Size: 9 x 17

Pin Count	153
Body Size	14 x 22

Outline Socket Dimensions (27.00 x 38.00mm)



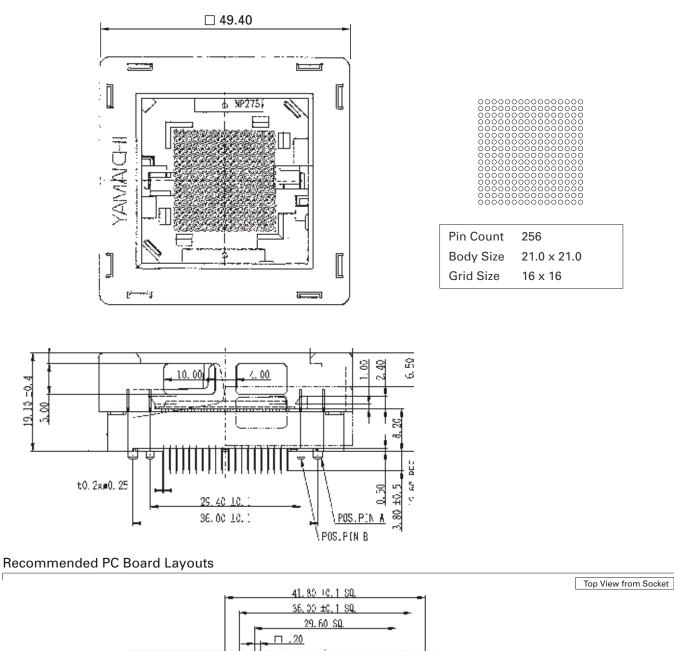
Pin Count	169
Body Size	17.0 x 17.0

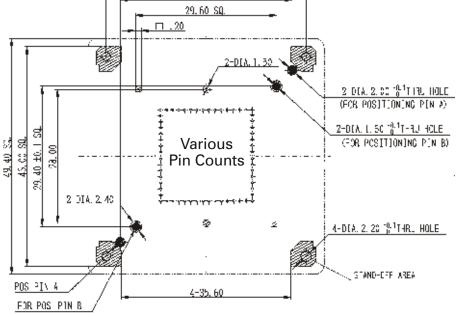
13 x 13

Grid Size

1 3 50 STROFE	
11. 70 ±4.5 BEF.	
11.11 14.20 BFL	
2.30 40.5	

Outline Socket Dimensions (49.4 x 49.4mm)

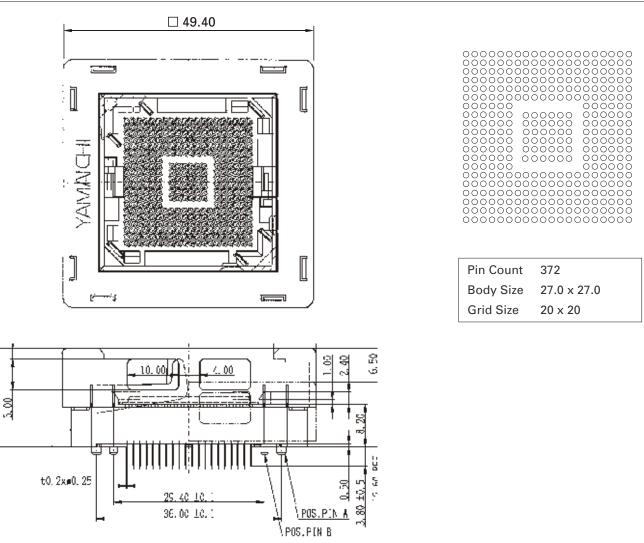




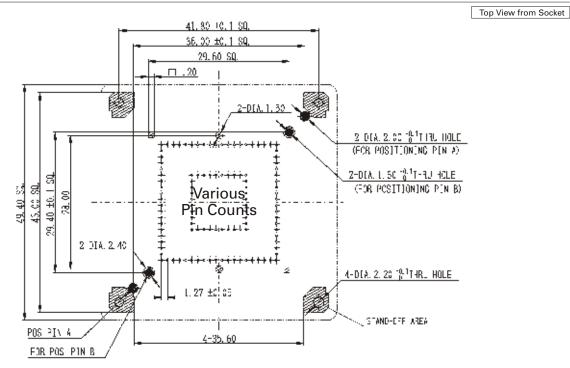
 19.10 ± 0.4 200



Outline Socket Dimensions (49.4 x 49.4mm)



Recommended PC Board Layouts

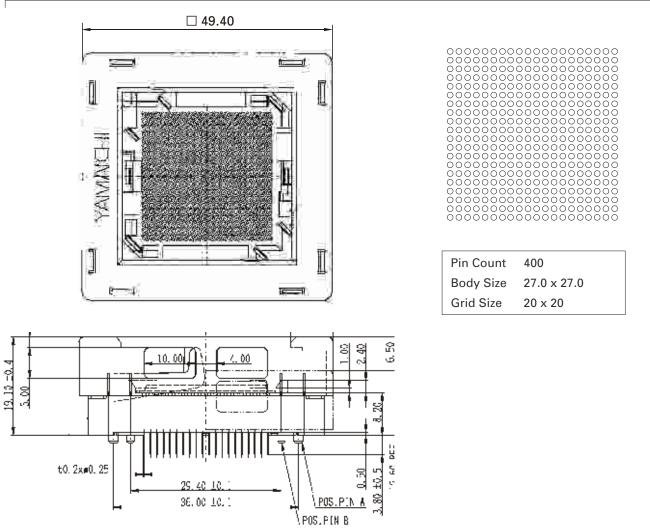


 19.10 ± 0.4

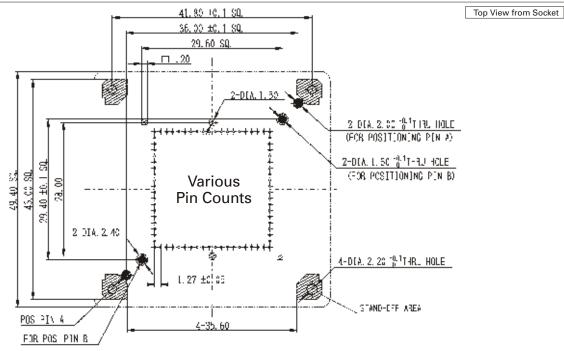
Ball Grid Array Base Socket (BGA, 1.27mm Pitch)

Base Socket NP276-40009

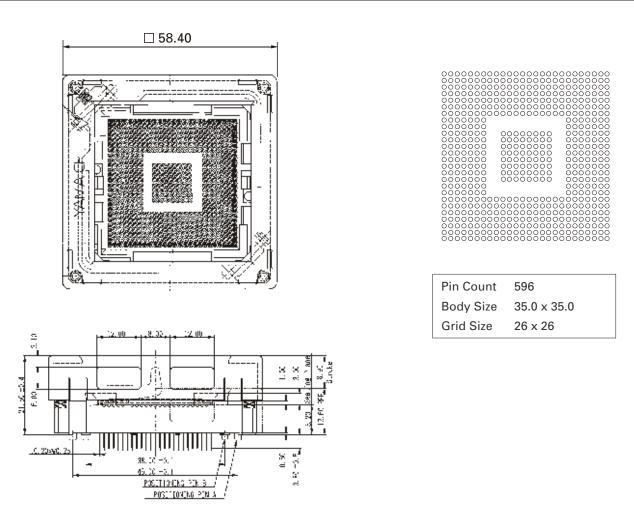
Outline Socket Dimensions (49.4 x 49.4mm)



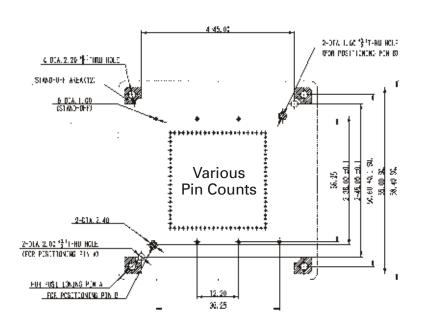
Recommended PC Board Layouts



Outline Socket Dimensions (58.4 x 58.4mm)

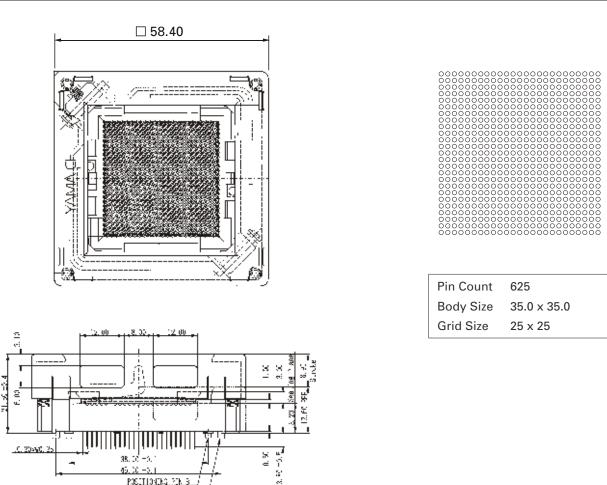


Recommended PC Board Layouts



Top View from Socket

Outline Socket Dimensions (58.4 x 58.4mm)

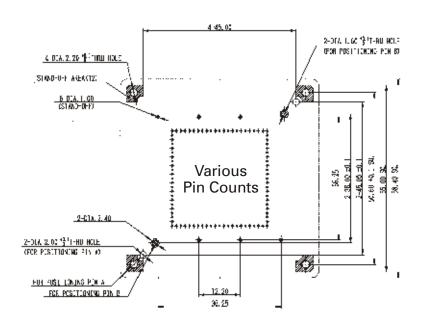


Recommended PC Board Layouts

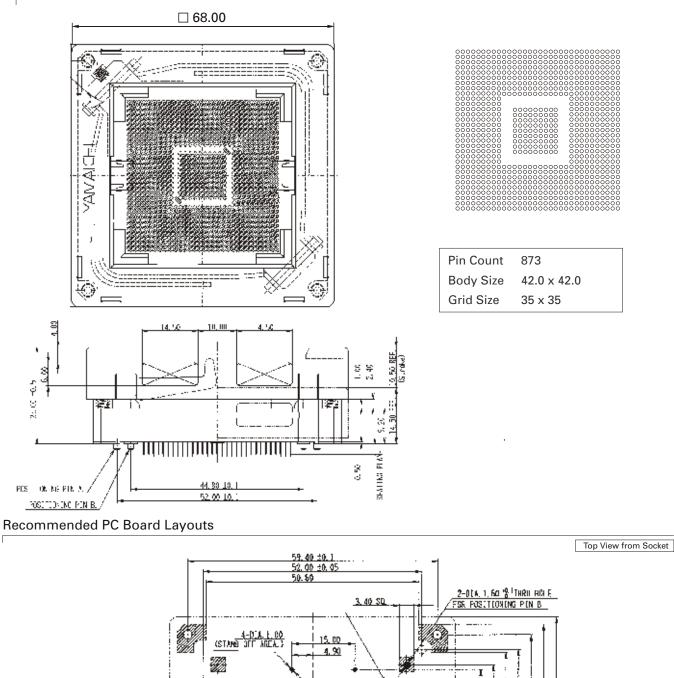
-

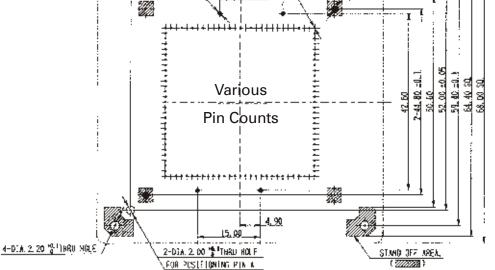
-0. POSITIONENS PER B POSCIEDNONG PON A

Top View from Socket



Outline Socket Dimensions (68.0 x 68.0mm)





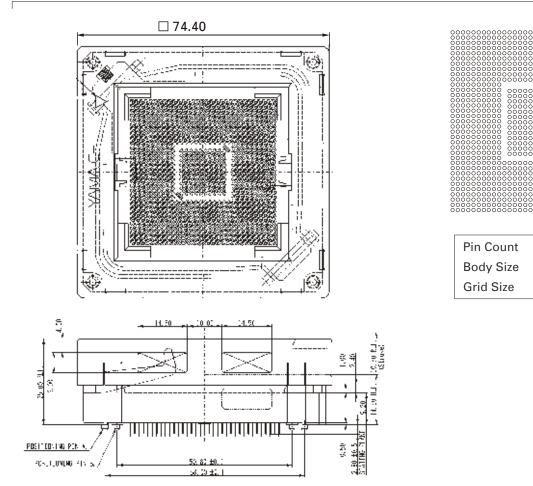
1105

45.0 x 45.0

35 x 35

Base Socket NP276-110522

Outline Socket Dimensions (74.0 x 74.0mm)



Recommended PC Board Layouts

